

**TO-252 N Channel Enhancement 沟道增强型
MOS Field Effect Transistor 场效应管**

■ **Features 特点**

Low on-resistance 低导通电阻

$R_{DS(ON)}=15.6m\Omega(\text{Type})@V_{GS}=10V$

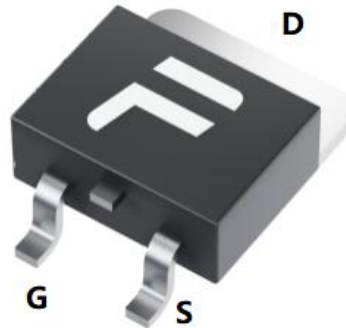
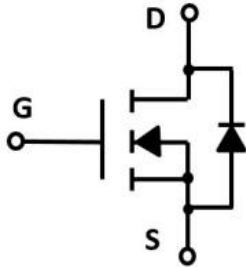
■ **Applications 应用**

Motor Driving in Power Tool,E-vehicle,Robotics 电动工具、电动汽车、机器人马达驱动

Current Switching in DC/DC&AC/DC(SR) Sub-systems 电源转换总线系统电流开关

Power Management in Telecom.,Industrial Automation 通信、工业自动化电源管理

■ **Internal Schematic Diagram 内部结构**



■ **Absolute Maximum Ratings 最大额定值**

Characteristic 特性参数	Symbol 符号	Rat 额定值	Unit 单位
Drain-Source Voltage 漏极-源极电压	BV_{DSS}	150	V
Gate- Source Voltage 栅极-源极电压	V_{GS}	± 20	V
Drain Current (continuous)漏极电流-连续	I_D (at $T_C = 25^\circ C$)	50	A
Drain Current (pulsed)漏极电流-脉冲	I_{DM}	200	A
Total Device Dissipation 总耗散功率	$P_{TOT}(\text{at } T_C = 25^\circ C)$	96	W
Thermal Resistance Junction-Case/Ambient 热阻	$R_{\theta JC}$ $R_{\theta JA}$	1.3 50	$^\circ C/W$
Avalanche Energy Single Pulse 雪崩能量	E_{AS}	135	mJ
Junction/Storage Temperature 结温/储存温度	T_J, T_{stg}	150 $^\circ C, -55\sim 150^\circ C$	

Electrical Characteristics 电特性

 (T_A=25°C unless otherwise noted 如无特殊说明, 温度为 25°C)

Characteristic 特性参数	Symbol 符号	Min 最小值	Typ 典型值	Max 最大值	Unit 单位
Drain-Source Breakdown Voltage 漏极-源极击穿电压(I _D =250uA, V _{GS} =0V)	BV _{DSS}	150	—	—	V
Gate Threshold Voltage 栅极开启电压(I _D =250uA, V _{GS} =V _{DS})	V _{GS(th)}	2.2	3.2	4.2	V
Zero Gate Voltage Drain Current 零栅压漏极电流(V _{GS} =0V, V _{DS} =150V)	I _{DSS}	—	—	1	uA
Gate Body Leakage 栅极漏电流(V _{GS} =±20V, V _{DS} =0V)	I _{GSS}	—	—	±100	nA
Static Drain-Source On-State Resistance 静态漏源导通电阻(I _D =20A, V _{GS} =10V)	R _{DS(ON)}	—	15.6	18.8	mΩ
Diode Forward Voltage Drop 内附二极管正向压降(I _{SD} =20A, V _{GS} =0V)	V _{SD}	—	—	1.2	V
Input Capacitance 输入电容 (V _{GS} =0V, V _{DS} =75V, f=1MHz)	C _{ISS}	—	2500	—	pF
Common Source Output Capacitance 共源输出电容(V _{GS} =0V, V _{DS} =75V, f=1MHz)	C _{OSS}	—	210	—	pF
Reverse Transfer Capacitance 反馈电容(V _{GS} =0V, V _{DS} =75V, f=1MHz)	C _{RSS}	—	20	—	pF
Total Gate Charge 栅极电荷密度 (V _{DS} =75V, I _D =20A, V _{GS} =10V)	Q _g	—	23	—	nC
Gate Source Charge 栅源电荷密度 (V _{DS} =75V, I _D =20A, V _{GS} =10V)	Q _{gs}	—	7.7	—	nC
Gate Drain Charge 栅漏电荷密度 (V _{DS} =75V, I _D =20A, V _{GS} =10V)	Q _{gd}	—	4.7	—	nC
Turn-ON Delay Time 开启延迟时间 (V _{DS} =75V I _D =20A, R _{GEN} =6Ω, V _{GS} =10V)	t _{d(on)}	—	7.1	—	ns
Turn-ON Rise Time 开启上升时间 (V _{DS} =75V I _D =20A, R _{GEN} =6Ω, V _{GS} =10V)	t _r	—	8.4	—	ns
Turn-OFF Delay Time 关断延迟时间 (V _{DS} =75V I _D =20A, R _{GEN} =6Ω, V _{GS} =10V)	t _{d(off)}	—	17	—	ns
Turn-OFF Fall Time 关断下降时间 (V _{DS} =75V I _D =20A, R _{GEN} =6Ω, V _{GS} =10V)	t _f	—	11	—	ns

■ Typical Characteristic Curve 典型特性曲线

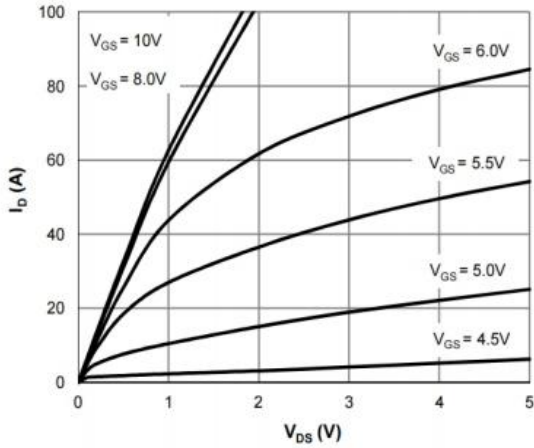


Figure 1: Output Characteristics

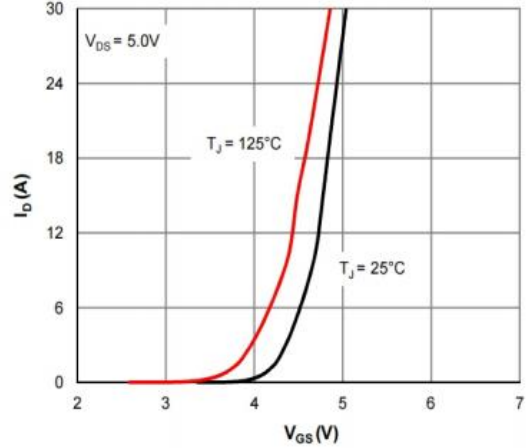


Figure 2: Transfer Characteristics

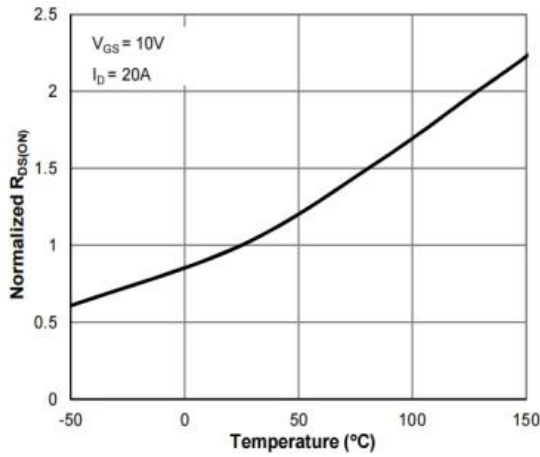


Figure 3: On-Resistance vs. T_J

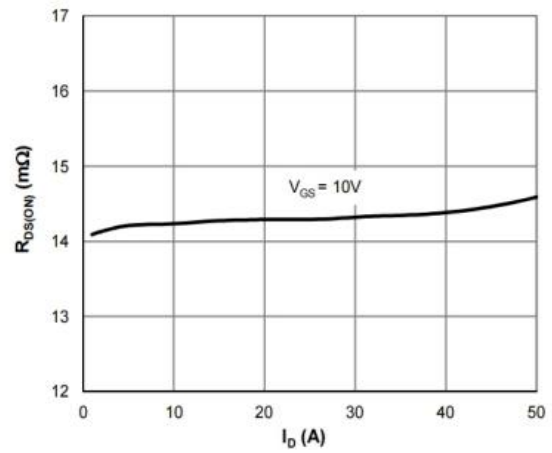


Figure 4: On-Resistance vs. Drain Current

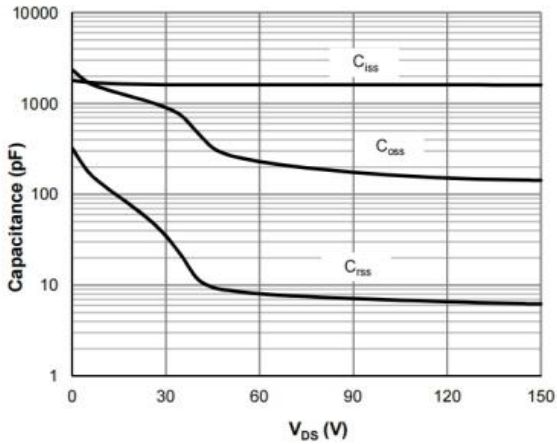


Figure 5: Capacitance Characteristics

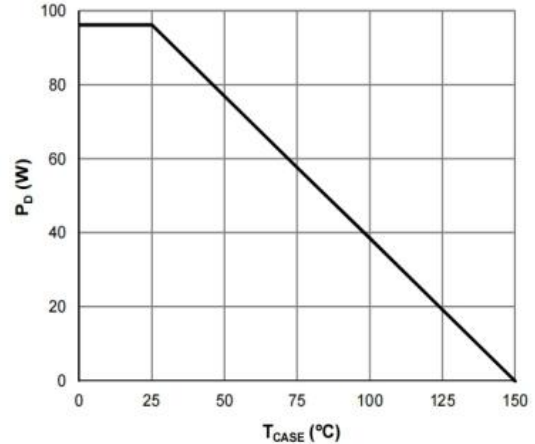


Figure 6: Power Characteristics

■ Typical Characteristic Curve 典型特性曲线

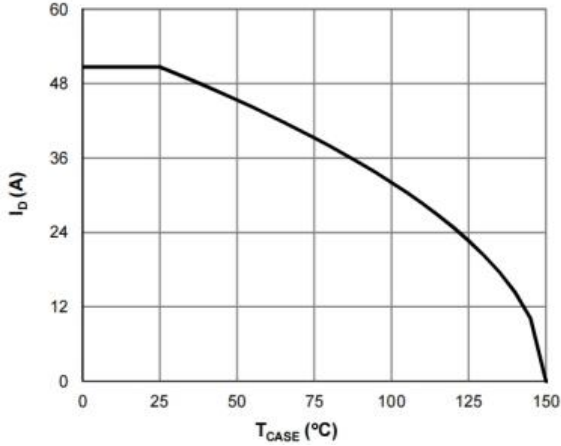


Figure 7: Drain Current Characteristics

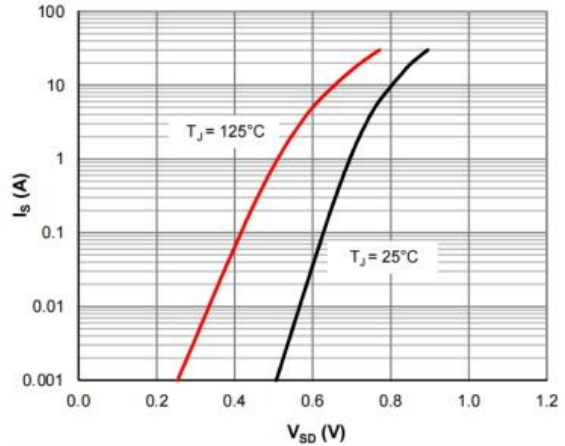


Figure 8: Diode Characteristics

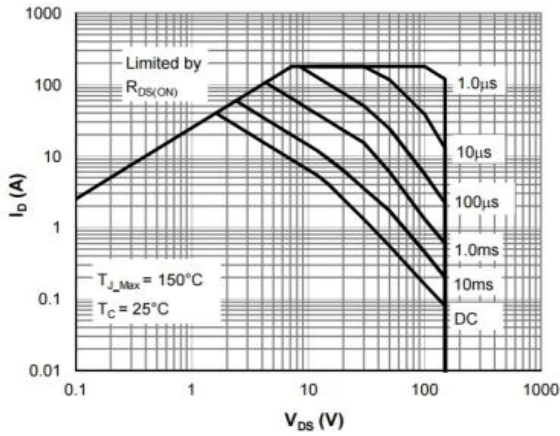


Figure 9: Safe Operating Area

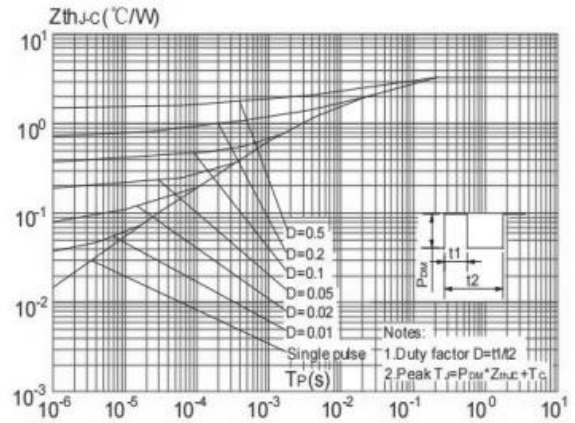


Figure 10: Transient Thermal Response Curve

■ Dimension 外形封装尺寸

